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(54) **Method to detect poor infrared rays, Microchip that is able to detect poor infrared rays and apparatus working with these microchips**

Verfahren zur Erkennung schwacher Infrarotstrahlen, zur Erkennung von schwachen Infrarotstrahlen fähiger Mikrochip und Vorrichtung mit diesen Mikrochips

Procédé pour détecter les faibles rayons infrarouges, micro-puce qui est capable de détecter les faibles rayons infrarouges et appareil fonctionnant avec ces micro-puces

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- **NORTON P: "HgCdTe infrared detectors", OPTO-ELECTRONICS REVIEW, WARSZAWA, PL, [Online] vol. 10, no. 3, 1 November 2002 (2002-11-01), pages 159-174, XP002599143, ISSN: 1230-3402 Retrieved from the Internet: URL:http://www.wat.edu.pl/review/optor/10(3)15 9.pdf> [retrieved on 2010-09-03]**

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Description

[0001] The invention relates to a method for the detection of poor rays of infrared wavelength, to a microchip that is able to detect poor infrared rays and to an apparatus working with these microchips.

[0002] In a closed body of a working machine or an electronic apparatus or a human or an animal body is to detect a source of little higher temperature than normal, when defects begin to happen. In an electronic apparatus more warmth as usual can appear when a resistance is stressed by a to high voltage, in a working machine is in the case of a lack of oil more warmth on a place produced which breaks at first, in a human or animal body arises the temperature where the body has to defend themselves against a growing cancer.

[0003] In all these cases the beginning of a growing defect can be located when it is possible to measure only a little higher temperature in a wide distance and to locate the place of this higher temperature.

[0004] This invention gives a possibility to detect and to locate little growings cancers and others hidden places of parts of a machine with increased temperature. The invention does it with a special microchip which is able to change photons in electrons. US5561295 discloses such a detector in which a continuous film of light detecting material is covered with a contact grid. This microchip of the invention consists of a plate of glass or an other insulating material with a rough surface on the one side. The front surface of this plate is rough by a plurality of blind holes, the ground of each of these blind holes is covered with a thin layer of metal, in each of the blind holes are located little semiconducting crystals of a kind of material that emits one or more electrons by each hit of an infrared light beam, the surface of this plate and the blind holes are covered with a net of very thin wires and the active part of this net of very thin wires has on its ends rails of metal to collect and transmit the electrons to a measuring instrument.

[0005] The blind holes can have the form of hemispheres, of cylindrical holes or honeycombs. Each blind hole has an inner surface of a thin layer of metal to deduct electrons from the surface or the edges of the crystals situated in the blind holes. From these metal layers and from the free edges of the crystals the thin wires covering the surface of the glass plate deduct the electrons to the rails and to the measuring instrument (to measure voltage differences).

[0006] The crystals put in the blind holes are semiconductors made from atoms of the group VI elements such as

<	Cadmium selenide	Cd Se
<	Cadmium sulfide	Cd Ss
<	Cadmium telluride	Cd Te
<	Zinc oxide	Zn O
<	Zinc selenide	Zn Se
<	Zinc sulfide	Zn S
<	Zinc telluride	Zn Te

and/or from II-VI ternary alloy semiconductors

<	Cadmium zinc telluride	Cd Zn Te
<	Mercury cadmium telluride	Hg Cd Te
<	Mercury zinc telluride	Hg Zn Te
<	Mercury zinc selenide	Hg Zn Se

and/or from a I-VII semiconductor

<	Cuprous chloride	Cu Cl
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and/or from IV - IV semiconductors

<	Lead selenide	Pb Se
<	Lead sulfide	Pb S
<	Lead telluride	Pb Te
<	Tin sulfide	Sn S
<	Tin telluride	Sn Te

and/or from IV - IV ternary semiconductors

< Lead tin telluride Pb Sn Te
< Thallium tin telluride Tl Sn Te
< Thallium germanium telluride Tl Ge Te

and/or from V - VI semiconductors

< Bismuth telluride Bi Te
< II - V semiconductors
< Cadmium phosphide Cd P

and/or from II - V semiconductors

< Cadmium phosphide Cd P
< Cadmium arsenide Cd As
< Cadmium antimonide Cd Sb
< Zinc phosphide Zn P
< Zinc arsenide Zn As
< Zinc antimonide Zn Sb

[0007] For this method it is useful if the crystals of the semiconductors are surrounded by a polymer which is grown in an acid fluid.

[0008] This polymer should be a good conductor of electrons like dendrimers and nanocarbon tube, especially

< Poly-acetylene
< Fullerenes
< Melamine
Poly-amidoamine
< non-polar polymers
< Fluoropolymers
< Fluorocarbons
< Polytetrafluoroethylene.

[0009] This invention relates also to a microchip that is able to detect poor infrared rays. This microchip consists of a thin plate of glass, silicon or another hard electrical insulating material, the front surface of this glass plate is rough by a plurality of blind holes, the ground of the blind holes is covered with a thin layer of metal, in the blind holes are situated little crystals of a kind of material that is an infrared absorber and emits one or more electrons by each hit of an infrared light beam, the surface of this plate of glass and the blind holes is covered with a net of very thin wires and the active part of this net of very thin wires has on its ends rails to collect the electrons.

[0010] This microchip is able to detect poor infrared rays and to change whose energy in electrons. That makes it possible to find out the presence and the power of an infrared radiation also in the case that this radiation is poor.

[0011] The microchip of the invention can have a front surface of grooves in form of a regular shape like little honeycombs.

[0012] It is advantageous if the crystals of this microchip located in the blind holes are surrounded by a polymer with electrical conductivity and/or some metal coating.

[0013] Because heat can be generated in the microchip of this invention the semiconductors or the these semiconductor carrying glass plate can be attached to or embedded in a heat deducting material.

[0014] It is advantageous for the construction of this microchip if the net of thin wires over the semiconductor crystals is so situated that they let through infrared light and catch the most of the in the semiconductors produced electrons.

[0015] To hinder a demolition of the microchip by sweat of a human body or oil of a machine or other influences it is advantageous to have a protection layer over the web of thin wires against a direct connection of the thin wires with the investigated body.

[0016] These microchips can be part of an apparatus for the detection of a source of poor infrared rays in a body

consisting of one or more microchips und a device for the comparison the output of electrons of the microchip(s) on diverse locations of the surface of the body, par example in an apparatus with one microchip to measure the ground-radiation of the body and another microchip to measure the soft increased radiation of a defect.

[0017] The enclosed drawing shows in

Fig.1 a view of the surface of the microchip.

Fig.2 a crossection through the microchip.

Fig.3 an enlarged part of the crossection.

Fig.4 a wiring diagramm of the apparatus using the microchips.

[0018] The microchip consists of a glas plate 1 with a rough surface on its front side, because there are many blind holes 2. In theese blind holes 2 are embedded cristals 3 of semiconductos surrounded by an acid polymer solution. The ground and the walls of the blind holes 2 are covered with a thin layer 4 of metal. Over the whole glas plate 1 with the cristals is laid a web of thin wires leading the electrons in the cristals produced electrons to the rails 5 acting as electrodes.

[0019] The apparatus 6 works with two microchips 7,8 on a body 9 to investigate. Microchip 7 is fastend on the body to ascertain the ground-radiation, microchip 8 is movable to find out a location with encreased radiation.

Claims

1. Method for producing a microchip that is able to detect poor rays of infrared wavelength by taking a thin plate of glass (1) or another hard electrical insulating material, the front surface is rough by a plurality of blind holes, (2) by covering the blind holes with a thin layer of metal, (4) by bringing in in the holes little crystals (3) of a kind of material that emits one or more electrons by each hit of an infrared light beam, by covering the surface of the plate and the blind holes with a net of very thin wires (5) and by collecting the electrons in rails (6) at the ends of the active part of the net of very thin wires and with semiconductors as crystals of a kind of material that emits one or more electrons by each hit of an infrared light beam.

2. Method for producing a microchip according claim 1 using crystals in the blind holes as

<	Cadmium selenide	Cd Se
<	Cadmium sulfide	Cd S
<	Cadmium telluride	Cd Te
<	Zinc oxide	Zn O
<	Zinc selenide	Zn Se
<	Zinc sulfide	Zn S
<	Zinc telluride	Zn Te

and/or from II - VI ternary alloy semiconductors

<	Cadmium zinc telluride	Cd Zn Te
<	Mercury cadmium telluride	Hg Cd Te
<	Mercury zinc telluride	Hg Zn Te
<	Mercury zinc selenide	Hg Zn Se

and/or from a I - VII semiconductor

<	Cuprous chloride	Cu Cl
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and/or from IV - IV semiconductors

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5	<	Lead selenide	Pb Se
	<	Lead sulfide	Pb S
	<	Lead telluride	Pb Te
	<	Tin sulfide	Sn S
	<	Tin telluride	Sn Te

and/or from IV - IV ternary semiconductors

10	<	Lead tin telluride	Pb Sn Te
	<	Thallium tin telluride	TI Sn Te
	<	Thallium germanium telluride	TI Ge Te

and/or from V - VI semiconductors

	<	Bismuth telluride	Bi Te
	<	II - V semiconductors	
20	<	Cadmium phosphide	Cd P

and/or from II - V semiconductors

25	<	Cadmium phosphide	Cd P
	<	Cadmium arsenide	Cd As
	<	Cadmium antimonide	Cd Sb
	<	Zinc phosphide	Zn P
30	<	Zinc arsenide	Zn As
	<	Zinc antimonide	Zn Sb

3. Method according claims 1 and 2 with semiconductors surrounded by a polymer which is grown in a acid fluid.

35 4. Method according claim 1 to 3 using a polymer which should be a good conductor of electrons like dendrimers and nanocarbon tube, especially

40	<	Poly-acetylene	
	<	Fullerenes	
	<	Melamine	
	<	Poly-amidoamine	
	<	non-polar polymers	
45	<	Fluoropolymers	
	<	Fluorocarbons	
	<	Polytetrafluoroethylene.	

50 5. Microchip

that is able to detect poor infrared rays consisting of a thin plate of glass (1) or another hard electrical insulating material, the front surface of this glass plate is rough by a plurality of blind holes, (2) the ground of the blind holes is covered with a thin layer of metal, (4) in the blind holes are situated little semiconductors crystals (3) of a kind of material that that is an infrared absorber and emits one or more electrons by each hit of an infrared light beam, the surface of this plate of glass and the blind holes is covered with a net of very thin wires (5) and the active part of this net of very thin wires has on its ends rails (6) to collect the electrons.

6. Microchip according claim 5

with a front surface of grooves in form of a regular shape like little honeycombs.

7. Microchip according claim 5
with crystals situated in the blind holes surrounded by a polymer with electrical conductivity.
8. Microchip according claim 5
whose semiconductors or glass plate are attached to or embedded in a heat deducted material.
9. Microchip according claim 7
with a net of thin wires over the semiconductor crystals so situated that they let through infrared light and catch the most of the in the semiconductors produced electrons.
10. Microchip according claim 5
with a protection layer over the web of thin wires against a direct connection of the thin wires with a investigated body.
11. Apparatus for the detection of a source of poor rays of infrared wavelength in a body consisting of one or more microchips according claim 5 and device for the comparison the output of electrons of the microchip(s) on diverse locations of the surface of the body.

Patentansprüche

1. Verfahren zur Herstellung eines Mikrochip, der in der Lage ist, schwache Strahlen von Infrarotwellenlänge zu erkennen, durch Verwenden einer dünnen Glasplatte (1) oder eines anderen harten elektrischen Isoliermaterials, dessen vordere Fläche durch eine Mehrzahl von Blindlöchern (2) aufgeraut ist, durch Bedecken der Blindlöcher mit einer dünnen Metallschicht (4), durch Einführen in die Löcher kleiner Kristalle (3) einer Art Material, das ein oder mehrere Elektronen durch jeden Treffer eines Infrarotlichtstrahls emittiert, durch Bedecken der Oberfläche der Platte und der Blindlöcher mit einem Netz aus sehr dünnen Drähten (5) und durch Auffangen der Elektronen in Schienen (6) an den Enden jedes aktive Teils des Netzes von sehr dünnen Drähten und mit Halbleitern als Kristallen irgendeiner Art Material, das ein oder mehrere Elektronen durch jeden Treffer eines Infrarotlichtstrahls emittiert.
2. Verfahren zur Herstellung eines Mikrochip nach Anspruch 1 unter Verwendung von Kristallen in den Blindlöchern als

<	Cadmiumselenid	Cd Se
<	Cadmiumsulfid	Cd S
<	Cadmiumtellurid	Cd Te
<	Zinkoxid	Zn O
<	Zinkselenid	Zn Se
<	Zinksulfid	Zn S
<	Zinktellurid	Zn Te

und/oder ternäre Legierungs-II - VI-Halbleiter

<	Cadmiumzinktellurid	Cd Zn Te
<	Quecksilbercadmiumtellurid	Hg Cd Te
<	Quecksilberzinktellurid	Hg Zn Te
<	Quecksilberzinkselenid	Hg Zn Se

und/oder I - VII-Halbleiter

<	Cuprochlorid	Cu Cl
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und/oder IV - IV-Halbleiter

<	Bleiselenid	Pb Se
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(fortgesetzt)

5	<	Bleisulfid	Pb S
	<	Bleitellurid	Pb Te
	<	Zinnsulfid	Sn S
	<	Zinntellurid	Sn Te

und/oder ternäre IV - IV-Halbleiter

10	<	Bleizinntellurid	Pb Sn Te
	<	Thalliumzinntellurid	Tl Sn Te
	<	Thalliumgermaniumtellurid	Tl Ge Te

15 und/oder V - VI-Halbleiter

	<	Wismuttellurid	Bi Te
	<	II - V-Halbleiter	
20	<	Cadmiumphosphid	Cd P

und/oder II - V-Halbleiter

25	<	Cadmiumphosphid	Cd P
	<	Cadmiumarsenid	Cd As
	<	Cadmiumantimonid	Cd Sb
	<	Zinkphosphid	Zn P
	<	Zinkarsenid	Zn As
30	<	Zinkantimonid	Zn Sb

3. Verfahren nach den Ansprüchen 1 und 2 mit Halbleitern, die von einem Polymer umgeben sind, das in einem sauren Fluid gezüchtet wird.

35 4. Verfahren nach Anspruch 1 bis 3, bei dem ein Polymer verwendet wird, das ein guter Leiter von Elektronen sein sollte, wie Dendrimere und Nanokohlenstoffröhren, insbesondere

40	<	Polyacetylen
	<	Fullerene
	<	Melamin
	<	Polyamidoamin
	<	nichtpolare Polymere
45	<	Fluorpolymere
	<	Fluorkohlenstoffe
	<	Polytetrafluorethylen.

50 5. Mikrochip, der in der Lage ist, schwache Infrarotstrahlen zu erkennen, bestehend aus einer dünnen Glasplatte (1) oder einem anderen harten elektrischen Isoliermaterial, wobei die vordere Fläche dieser Glasplatte durch eine Mehrzahl von Blindlöchern (2) aufgeraut ist, wobei der Boden der Blindlöcher mit einer dünnen Metallschicht (4) bedeckt ist, in den Blindlöchern sich kleine Halbleiterkristalle (3) einer Art Material befinden, das ein Infrarotabsorptionsmittel ist und ein oder mehrere Elektronen durch jeden Treffer eines Infrarotlichtstrahls emittiert, die Oberfläche dieser Glasplatte und die Blindlöcher mit einem Netz aus sehr dünnen Drähten (5) bedeckt sind und der aktive Teil dieses Netzes von sehr dünnen Drähten Schienen (6) an seinen Enden zum Auffangen der Elektronen aufweist.

6. Mikrochip nach Anspruch 5 mit einer vorderen Oberfläche von Vertiefungen in Form einer regelmäßigen Gestalt

wie kleiner Waben.

7. Mikrochip nach Anspruch 5 mit Kristallen, die sich in den Blindlöchern befinden und von einem Polymer mit elektrischer Leitfähigkeit umgeben sind.
8. Mikrochip nach Anspruch 5 dessen Halbleiter oder Glasplatte an einem wärmeabgezogenen Material befestigt oder darin eingebettet sind.
9. Mikrochip nach Anspruch 7 mit einem Netz dünner Drähte über den Halbleiterkristallen, die so positioniert sind, dass sie Infrarotlicht hindurchlassen und den Hauptteil der in den Halbleitern erzeugten Elektronen auffangen.
10. Mikrochip nach Anspruch 5 mit einer Schutzschicht über dem Netzwerk dünner Drähte gegen eine direkte Verbindung der dünnen Drähte mit einem untersuchten Körper.
11. Apparat zur Erkennung einer Quelle schlechter Strahlen einer Infrarotwellenlänge in einem Körper, bestehend aus einem oder mehreren Mikrochip nach Anspruch 5 und Vorrichtung zum Vergleichen der Abgabe von Elektronen des/der Mikrochip an verschiedenen Stellen der Oberfläche des Körpers.

Revendications

1. Procédé de production d'une micropuce qui est capable de détecter les faibles rayons de longueur d'onde infrarouge en utilisant une plaque mince de verre (1) ou un autre matériau isolant électrique dur, la surface avant est rendue rugueuse par une pluralité de trous borgnes (2), en recouvrant les trous borgnes avec une couche mince de métal (4), en amenant dans les trous de petits cristaux (3) d'un type de matériau qui émet un ou plusieurs électrons à chaque atteinte d'un faisceau de lumière infrarouge, en recouvrant la surface de la plaque et les trous borgnes d'un réseau de fils très minces (5) et en recueillant les électrons dans des rails (6) aux extrémités de la partie active du réseau de fils très minces et avec des semi-conducteurs en tant que cristaux d'un type de matériau qui émet un ou plusieurs électrons à chaque atteinte d'un faisceau de lumière infrarouge.
2. Procédé de production d'une micropuce selon la revendication 1 utilisant des cristaux dans les trous borgnes sous forme de

<	séléniumure de cadmium	Cd Se
<	sulfure de cadmium	Cd S
<	tellurure de cadmium	Ce Te
<	oxyde de zinc	Zn O
<	séléniumure de zinc	Zn Se
<	sulfure de zinc	Zn S
<	tellurure de zinc	Zn Te

et/ou de semi-conducteurs d'alliages ternaires II - VI

<	tellurure de zinc-cadmium	Cd Zn Te
<	tellurure de mercure-cadmium	Hg Cd Te
<	tellurure de mercure-zinc	Hg Zn Te
<	séléniumure de mercure-zinc	Hg Zn Se

et/ou de semi-conducteurs I - VII

<	chlorure de cuivre	Cu Cl
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et/ou de semi-conducteurs IV - IV

<	séléniumure de plomb	Pb Se
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(suite)

5	<	sulfure de plomb	Pb S
	<	tellure de plomb	Pb Te
	<	sulfure d'étain	Sn S
	<	tellure d'étain	Sn Te

et/ou de semi-conducteurs d'alliages ternaires IV - IV

10	<	tellure de plomb-étain	Pb Sn Te
	<	tellure de thallium-étain	Tl Sn Te
	<	tellure de thallium-germanium	Tl Ge Te

15 et/ou de semi-conducteurs V - VI

20	<	tellure de bismuth	Bi Te
	<	semi-conducteurs II - V	
	<	phosphure de cadmium	Cd P

et/ou de semi-conducteurs II - V

25	<	phosphure de cadmium	Cd P
	<	arséniure de cadmium	Cd As
	<	antimoine de cadmium	Cd Sb
	<	phosphure de zinc	Zn P
	<	arséniure de zinc	Zn As
	<	antimoine de zinc	Zn Sb.

3. Procédé selon les revendications 1 et 2 avec des semi-conducteurs entourés par un polymère qui est développé dans un fluide acide.

4. Procédé selon les revendications 1 à 3 utilisant un polymère qui doit être un bon conducteur pour les électrons tels que les dendrimères et un nanotube de carbone, en particulier

40	<	un polyacétylène	
	<	les fullerènes	
	<	une mélamine	
	<	une polyamidoamine	
	<	des polymères non polaires	
	<	des polymères fluorés	
45	<	des hydrocarbures fluorés	
	<	un polytétrafluoroéthylène.	

5. Micropuce qui est capable de détecter les faibles rayons de longueur d'onde infrarouge en utilisant une plaque mince de verre (1) ou un autre matériau isolant électrique dur, la surface avant est rendue rugueuse par une pluralité de trous borgnes (2), la zone des trous borgnes est recouverte d'une couche mince de métal (4), dans les trous borgnes sont situés de petits cristaux de semi-conducteurs (3) d'un type de matériau qui est un absorbeur d'infrarouge et émet un ou plus électrons à chaque atteinte d'un faisceau de lumière infrarouge, la surface de cette plaque de verre et des trous borgnes est recouverte d'un réseau de fils très minces (5) et la partie réactive de ce réseau de fils très minces a sur ses extrémités des rails qui recueillent les électrons.

6. Micropuce selon la revendication 5 ayant une surface avant constituée de rainures sous la forme d'une forme

régulière telle que de petits nids d'abeilles.

7. Micropuce selon la revendication 5 ayant des cristaux situés dans les trous borgnes entourés par un polymère ayant une conductivité électrique.

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8. Micropuce selon la revendication 5 dont les semi-conducteurs ou la plaque de verre sont attachés à ou ancrés dans un matériau déduit par la chaleur.

9. Micropuce selon la revendication 7 ayant un réseau de fils minces sur les cristaux de semi-conducteurs placés de telle sorte qu'ils laissent passer la lumière infrarouge et attrapent la plupart des électrons produits par les semi-conducteurs.

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10. Micropuce selon la revendication 5 ayant une couche de protection sur le réseau de fils minces empêchant une connexion directe des fils minces avec un corps étudié.

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11. Appareil de détection d'une source de faibles rayons de longueur d'onde infrarouge dans un corps constitué par une ou plusieurs micropuces selon la revendication 5 et un dispositif permettant la comparaison de la sortie des électrons de la ou des micropuces en divers endroits de la surface du corps.

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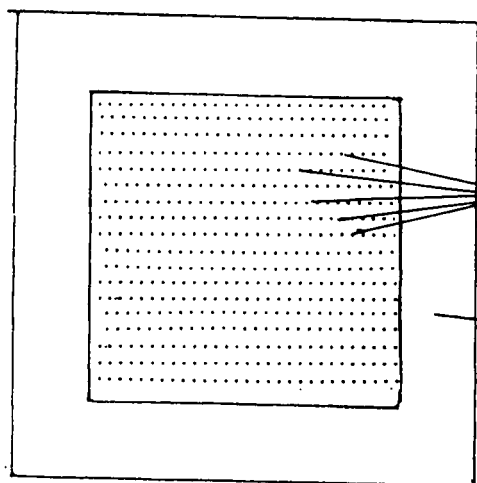


FIG. 1

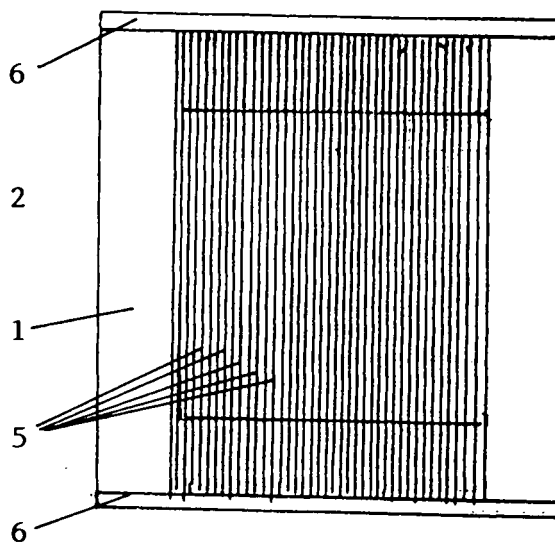


FIG. 2

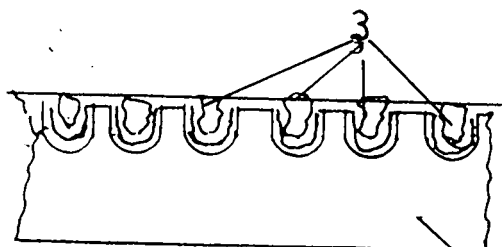


FIG. 3

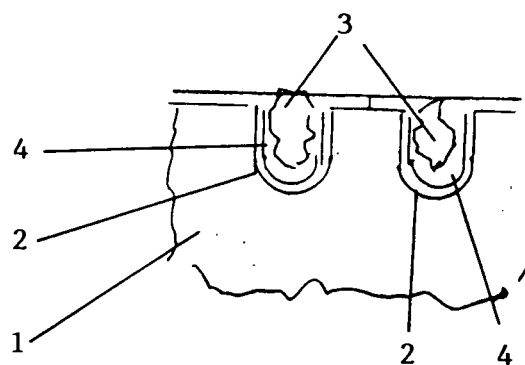
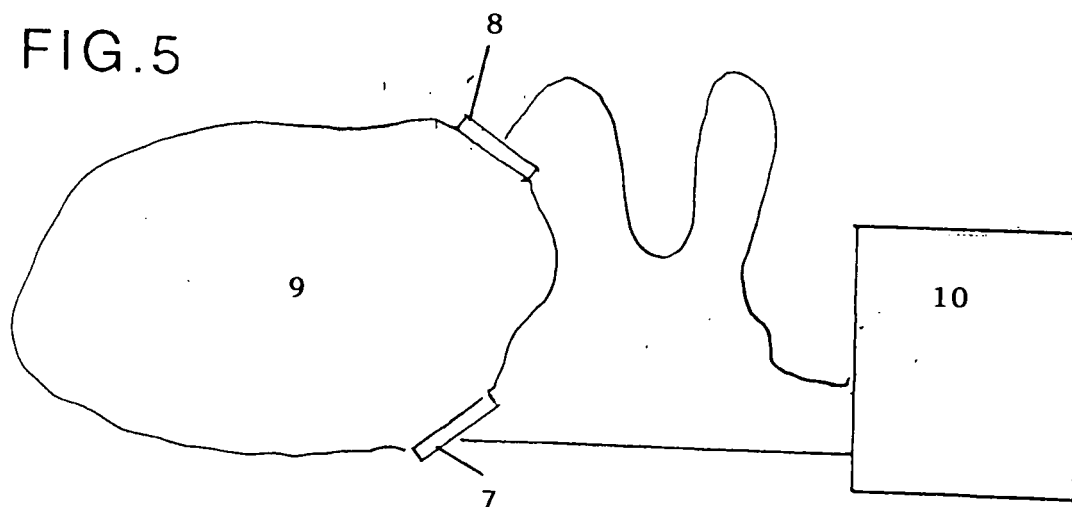


FIG. 4

FIG. 5



REFERENCES CITED IN THE DESCRIPTION

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Patent documents cited in the description

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专利名称(译)	检测较差红外线的方法，能够检测较差红外线的Microchip和使用这些微芯片的设备		
公开(公告)号	EP2051303B1	公开(公告)日	2017-07-05
申请号	EP2008013302	申请日	2008-07-24
[标]申请(专利权)人(译)	仿生TECH		
申请(专利权)人(译)	仿生科技股份有限公司.		
当前申请(专利权)人(译)	仿生科技股份有限公司.		
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摘要(译)

本发明涉及一种用于检测红外波长的不良光线的方法，一种能够检测不良红外线的微芯片以及一种使用这些微芯片的设备。本发明提供了检测和定位具有增加的温度的机器部件的小的生长癌症和其他隐藏位置的可能性。本发明使用能够改变电子中的光子的特殊微芯片来做到这一点。本发明的微芯片由一块玻璃板或其它绝缘材料构成，在一侧具有粗糙表面。这个板的前表面是由多个盲孔粗糙的，每个盲孔的地面都覆盖着一层薄薄的金属，每个盲孔都放置一种发射一种材料的小晶体。每次击中红外光束或更多的电子，该板的表面和盲孔都覆盖着非常细的电线网，这种非常细的电线网的有源部分在其端部有金属轨道来收集并将电子传输到测量仪器。

